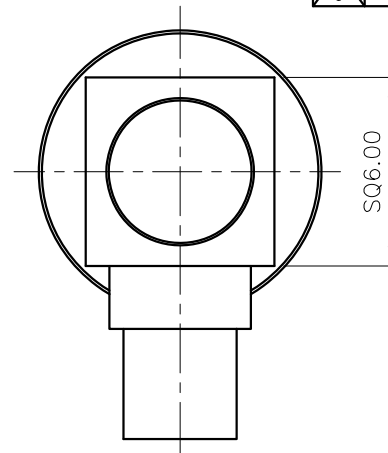
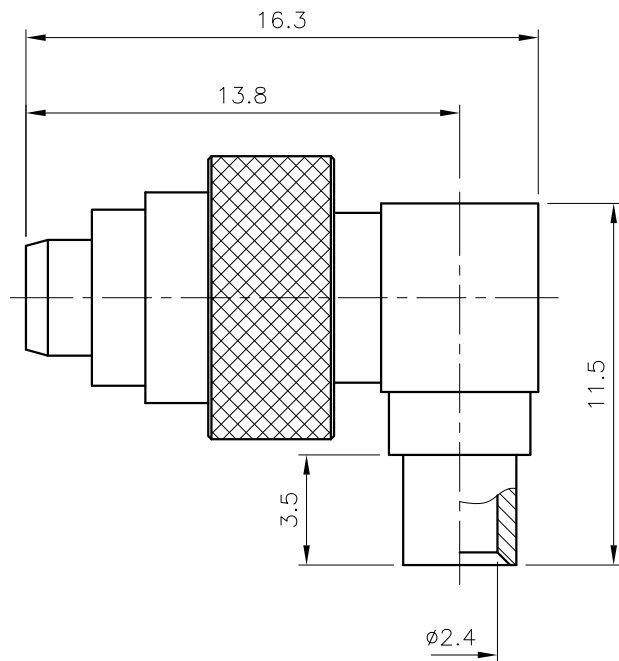
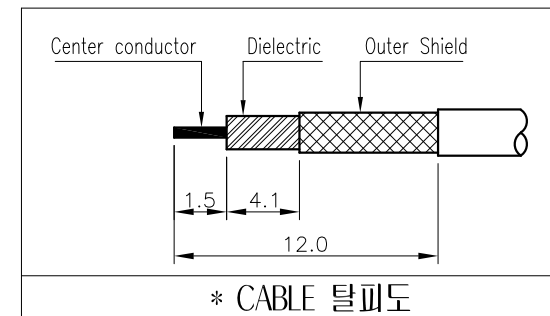


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2014. 12. 22.
1	[설번처리No.201504-0002] 메이팅부 치수 표준화 적용	H.J.LEE	I.C.KIM	2015. 04. 23.
2	[설번처리No.201601-0009] COVER 눌림 현상 발생으로 높이 치수 변경 및 면취 추가	H.J.LEE	I.C.KIM	2016. 01. 13.
3	[설번처리No.201605-0012] COVER 조립시 BURR가 생겨 쇼트 발생으로 COVER 변경	H.J.LEE	I.C.KIM	2016. 05. 25.
4	[설번No.201709-0004] PIN MATING부 접촉 개선으로 인한 치수 변경	S.Y.EUN	I.C.KIM	2017. 10. 17.
5	바디 내부 및 절연체 인자 구조로 변경	S.H.KIM		2023. 08. 23.



8	SPRING	1	SUS	Passivate	DSR01102-5/1
7	COVER	1	MBsBD C3604BD-F	Nickel Plate	DCO00111-5/1 DCO00020-5/2
6	CAP	1	MBsBD C3604BD-F	Nickel Plate	DCU02233-5/2
5	INSULATOR	1	TEFLON		DIN02021-N/7 DIN02021-N/1
4	FERRULE	1	MBsBD C3604BD-F	Nickel Plate	DFE00161-5/1
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03328-5/2 DCT03328-5/1
2	BODY (B)	1	MBsBD C3604BD-F	Nickel Plate	DBD03456-5/4 DBD03456-5/2
1	BODY (A)	1	MBsBD C3604BD-F	Nickel Plate	DBD03817-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2023. 08. 23.			 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle ±1°	APPROVED BY			
MATERIAL _____	CHECKED BY			TITLE SMBL50 CABLE PL MF86(50Ω) Solder+FERRULE/CRIMP	
	DRAWN BY S.H.KIM				
FINISH _____	SCALE 4/1	UNIT mm		A4	DWG NO. CN02825-7/4
					REVISION 5